



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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1

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LOC

DIST

REVISIONS

DW

P

LTR

DESCRIPTION

DATE

DWN

APVD

B1

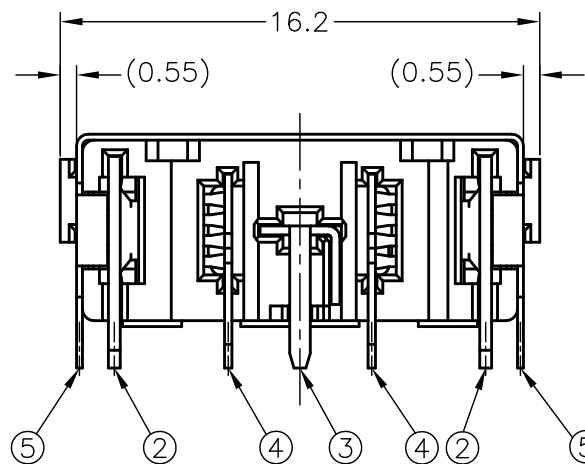
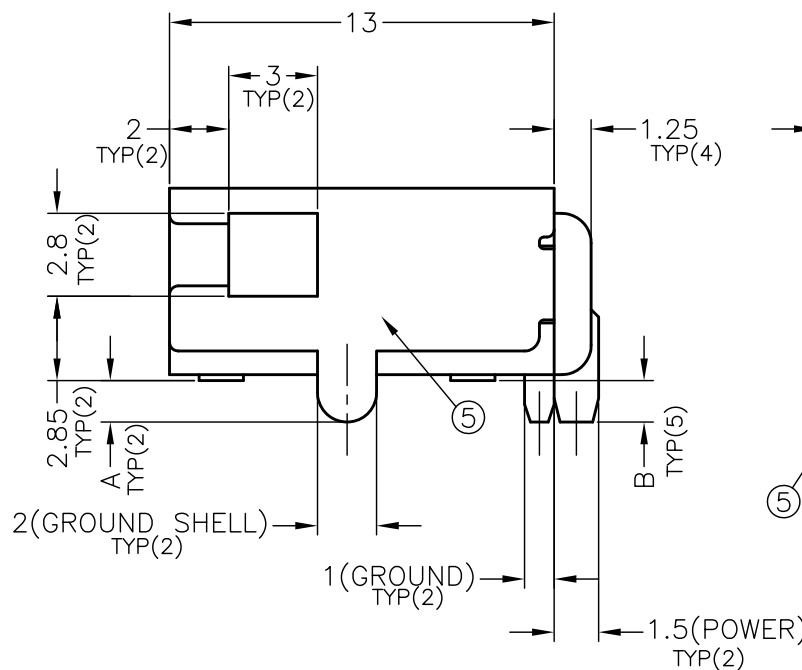
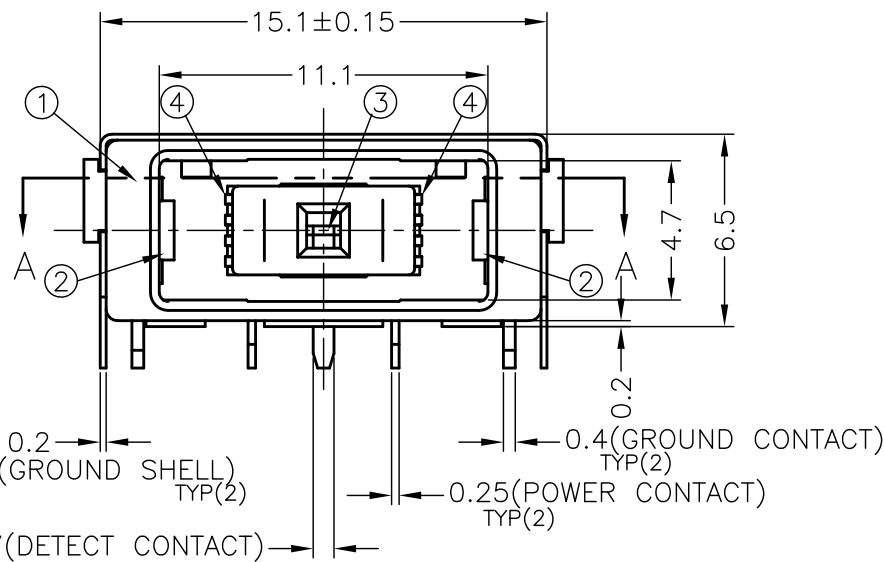
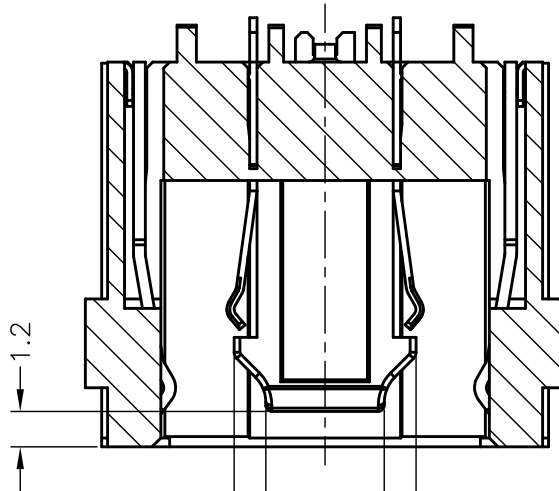
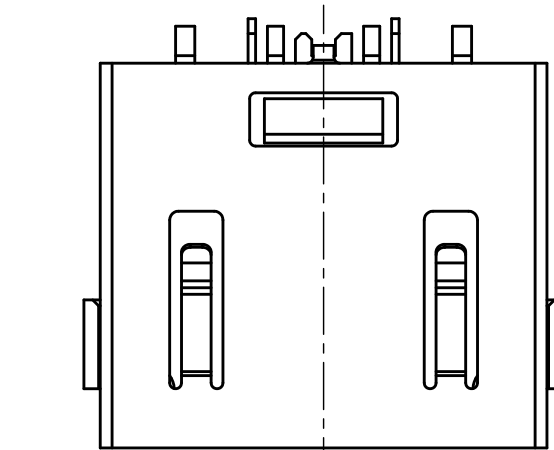
REVISED (ECR-13-009702)

7MAY13

S.H

V.P

1. EU ROHS-RELATED RESTRICTED SUBSTANCE SPEC IN HOMOGENEOUS MATERIAL REFER TO TEC-138-702 REV.G:
LEAD < 1000PPM, CADMIUM < 100PPM, MERCURY < 1000PPM
CHROMIUM VI < 1000PPM, PBB <1000PPM, PBDE < 1000PPM
2. HALOGEN FREE SPEC:
CHLORINE (Cl): 900 ppm MAX.
BROMINE (Br): 900 ppm MAX.
CHLORINE (Cl) + BROMINE (Br): 1500 ppm MAX.

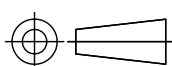


A'SSY P/N				
	1-2129458-2	1-2129458-1	2129458-2	2129458-1
DIM B	1.2	1.4	1.2	1.4
DIM A	1.2	1.4	1.2	1.4
Q'TY	1	1	2	2

1	1	0.002mm MATTE TIN PLATING ON SOLDER AREA, 0.00127mm MIN. NICKEL UNDERPLATED ALL OVER	COPPER ALLOY	GROUND SHELL	⑤
2	2	0.0002mm GOLD PLATING ON CONTACT AREA, 0.002mm MATTE TIN PLATING ON SOLDER AREA, 0.002mm MIN. NICKEL UNDERPLATED ALL OVER	COPPER ALLOY	POWER CONTACT	④
1	1	0.0002mm GOLD PLATING ON CONTACT AREA, 0.002mm MATTE TIN PLATING ON SOLDER AREA, 0.002mm MIN. NICKEL UNDERPLATED ALL OVER	COPPER ALLOY	DETECT CONTACT	③
2	2	0.0002mm GOLD PLATING ON CONTACT AREA, 0.002mm MATTE TIN PLATING ON SOLDER AREA, 0.002mm MIN. NICKEL UNDERPLATED ALL OVER	COPPER ALLOY	GROUND CONTACT	②
1	1	BLACK	HIGH TEMPERATURE THERMO-PLASTIC (UL94V-0)	HOUSING	①
FINISH/COLOR			MATERIAL	PART NAME	NO.

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS:
mm



MATERIAL

SEE TABLE

TOLERANCES UNLESS OTHERWISE SPECIFIED:

0-PLC ±
1-PLC ±
2-PLC ±
3-PLC ±
4-PLC ±
ANGLES ±
FINISH ±

DWN 20JUN2012

S.HUANG

CHK 20JUN2012

V.PENG

APVD 20JUN2012

W.KODAMA

PRODUCT SPEC

108-99040

APPLICATION SPEC

501-99041

WEIGHT 1.94g

CUSTOMER DRAWING



TE Connectivity

DC POWER JACK CONNECTOR
DIP TYPE (10.7A)

SIZE

CAGE CODE

DRAWING NO

RESTRICTED TO

A3

00779

2129458

SCALE

4:1

SHEET

1 of 3

REV

B1

4

3

2

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DESCRIPTION

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DWN

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SEE SHEET 1

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D

D

C

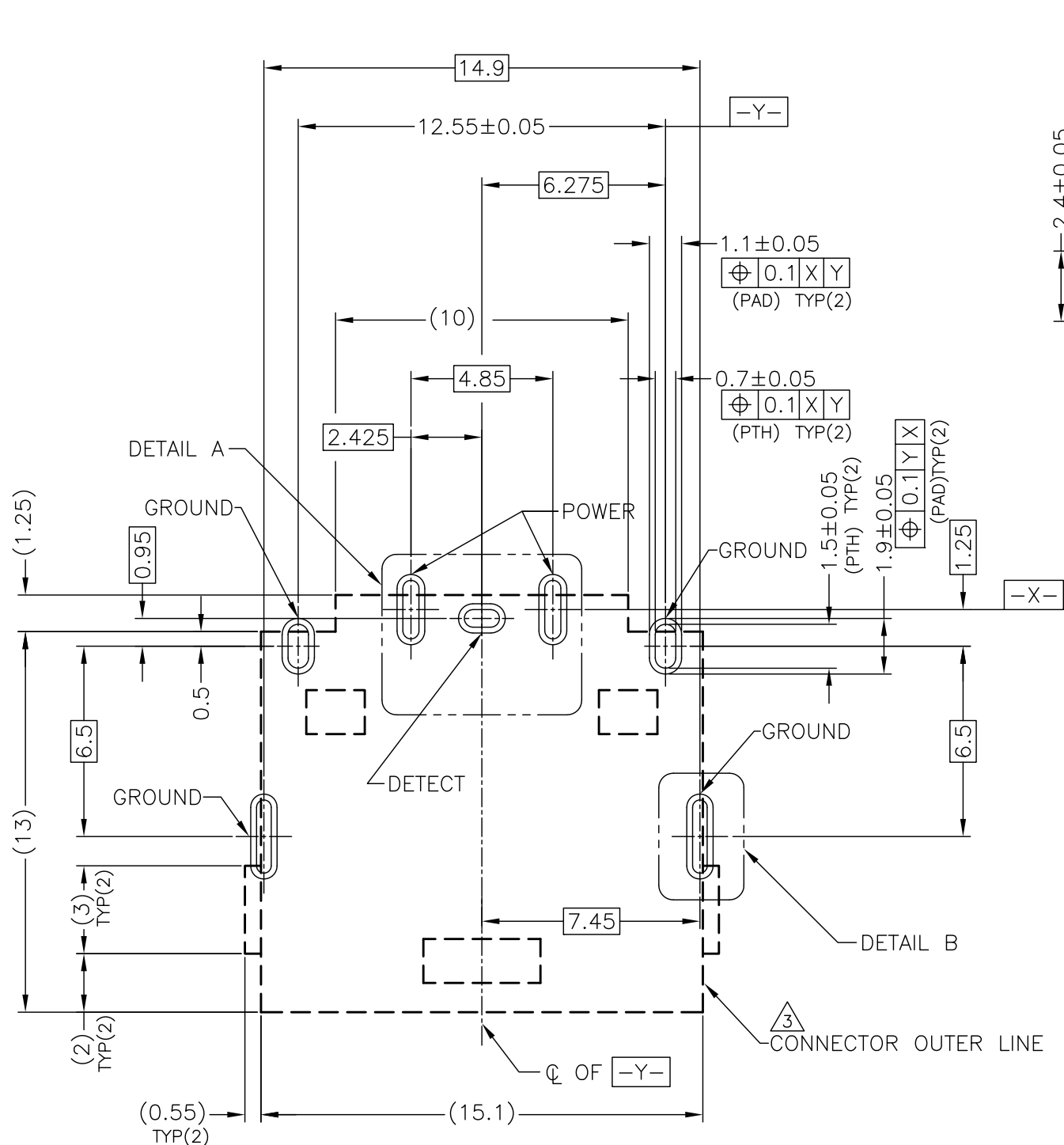
C

B

B

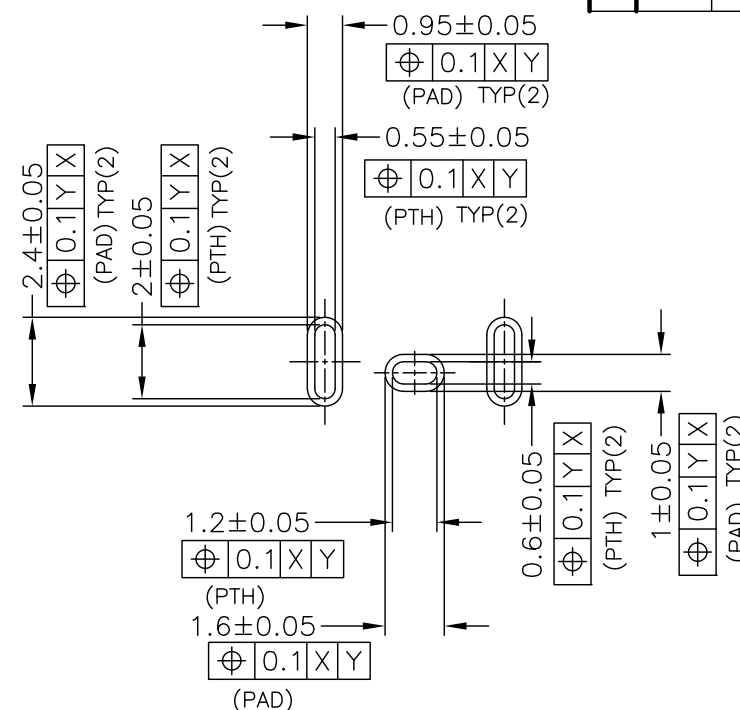
A

A

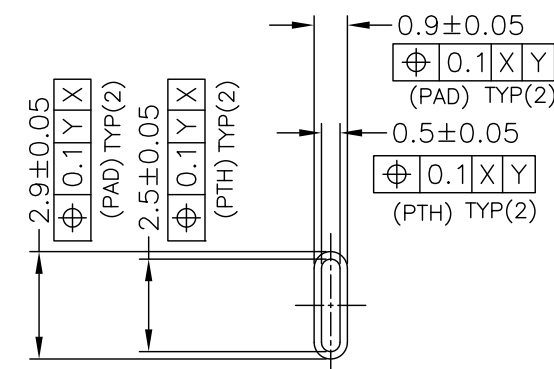


RECOMMENDED P.C.BOARD PATTERN LAYOUT (TOP VIEW)
TOLERANCE:±0.05 (THICKNESS=0.8mm)

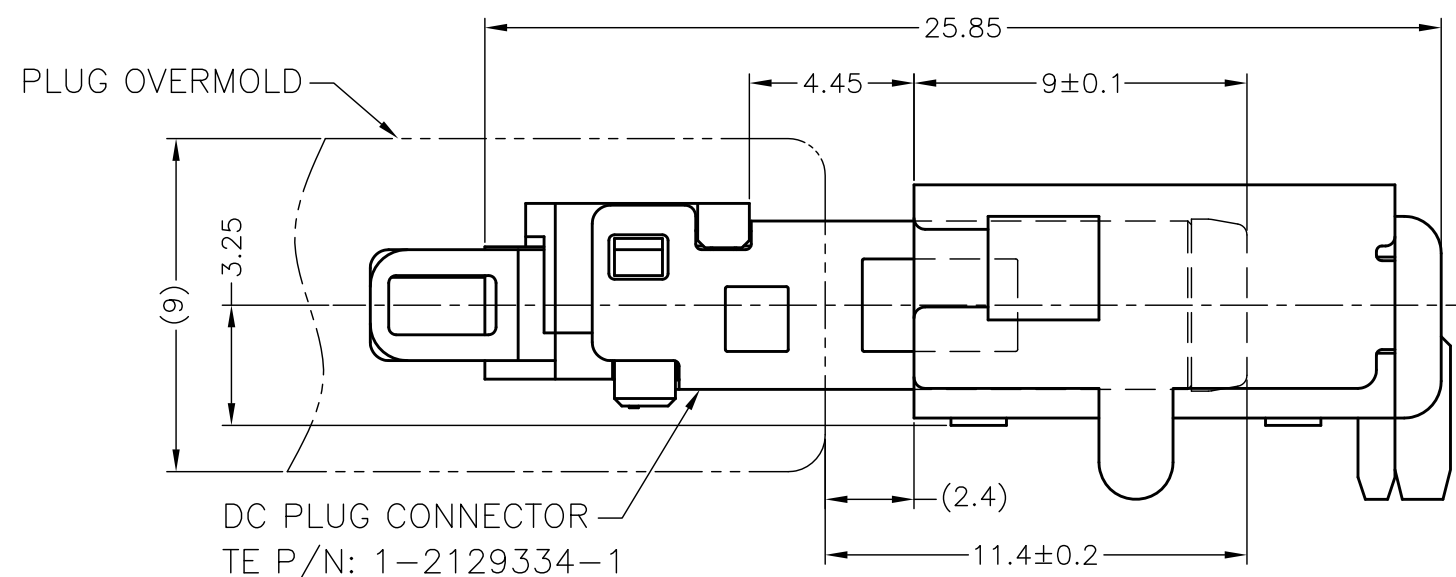
△ [] : CONNECTOR OUTER LINE (NO COMPONENT AREA)



DETAIL A



DETAIL B



MATING CONDITION

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DWN

CHK

APVD

PRODUCT SPEC

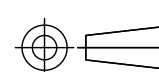
APPLICATION SPEC

WEIGHT

CUSTOMER DRAWING

DIMENSIONS:

mm



TOLERANCES UNLESS OTHERWISE SPECIFIED:

0-PLC ±-
1-PLC ±-
2-PLC ±- ±0.25
3-PLC ±- ±3°
4-PLC ±-
ANGLES ±-
FINISH

MATERIAL

STE

TE Connectivity

NAME

DC POWER JACK CONNECTOR
DIP TYPE (10.7A)

SIZE

CAGE CODE

DRAWING NO

RESTRICTED TO

A3

00779

C-2129458

SCALE

5:1

SHEET

2 OF 3

REV

B1

